

N-Channel Enhancement Mode MOSFET

1. Product Information

1.1 Features

- Advanced trench cell design
- Low Thermal Resistance

1.2 Applications

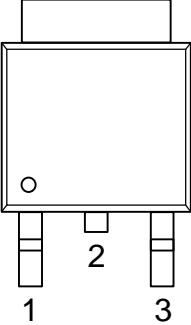
- Motor drivers
- DC-DC Converter

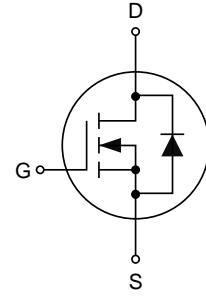
1.3 Quick reference

- $BV \geq 100 \text{ V}$
- $P_{\text{tot}} \leq 96 \text{ W}$
- $I_D \leq 85 \text{ A}$
- $R_{DS(\text{ON})} \leq 7.0 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$
- $R_{DS(\text{ON})} \leq 8.8 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$

2. Pin Description

Pin	Description	Simplified Outline	Symbol
1	Gate(G)		
2	Drain(D)		
3	Source(S)		


**Top View
TO-252**



**KJ07N10KM**

3. Limiting Values

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	Drain-Source Voltage	T _C =25°C	100	-	V
V _{GS}	Gate-Source Voltage	T _C =25°C	-	±20	V
I _D *	Drain Current (DC)	T _C =25°C, V _{GS} =10V	-	85	A
I _D *	Drain Current (DC)	T _C =100°C, V _{GS} =10V	-	54	A
I _{DM} **,***	Drain Current (Pulsed)	T _C =25°C, V _{GS} =10V	-	340	A
P _{tot}	Total Power Dissipation	T _C =25°C	-	96	W
T _{stg}	Storage Temperature		-55	150	°C
T _J	Junction Temperature		-	150	°C
I _S	Diode Forward Current	T _C =25°C	-	84	A
E _{AS} *	Single Pulsed Avalanche Energy	V _{DD} =50V, L=0.3mH	-	265	mJ
R _{θJA} *	Thermal Resistance- Junction to Ambient		-	42.6	°C/W
R _{θJC} *	Thermal Resistance- Junction to Case		-	1.3	

Notes:

* Surface Mounted on 1 in² pad area, t ≤ 10 sec

** Pulse width ≤ 300 μs, duty cycle ≤ 2 %

*** Limited by bonding wire

4. Marking Information

Product Name	Marking
KJ07N10KM	KJ07N10KM XXXXXX

5. Ordering Code

Product Name	Package	Reel size	Tape width	Quantity (pcs)
KJ07N10KM	TO-252	13"	16 mm	2500

Note: KUAIJIEXIN defines "Green" as lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900 ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500 ppm by weight; Follow IEC 61249-2-21 and IPC/JEDEC J-STD-020C)

**KJ07N10KM**

6. Electrical Characteristics ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{ V}$, $I_{DS}=250\text{ }\mu\text{A}$	100	-	-	V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250\text{ }\mu\text{A}$	1.2	-	2.5	V
I_{DSS}	Zero Gate Voltage Source Current	$V_{DS}=80\text{ V}$, $V_{GS}=0\text{ V}$	-	-	1	μA
I_{GSS}	Gate Leakage Current	$V_{DS}=0\text{ V}$, $V_{GS}=\pm 20\text{ V}$	-	-	± 100	nA
$R_{DS(ON)}^a$	On-State Resistance	$V_{GS}=10\text{ V}$, $I_{DS}=20\text{ A}$	-	5.5	7.0	$\text{m}\Omega$
		$V_{GS}=4.5\text{ V}$, $I_{DS}=10\text{ A}$	-	6.5	8.8	
Diode Characteristics						
V_{SD}^a	Diode Forward Voltage	$I_{SD}=20\text{ A}$, $V_{GS}=0\text{ V}$	-	0.9	1.3	V
t_{rr}	Reverse Recovery Time	$I_{DS}=20\text{ A}$, $V_{GS}=0\text{ V}$ $dI_{SD}/dt=100\text{ A}/\mu\text{s}$	-	70	-	ns
Q_{rr}	Reverse Recovery Charge		-	45	-	nC
Dynamic Characteristics ^b						
C_{iss}	Input Capacitance	$V_{GS}=0\text{ V}$, $V_{DS}=50\text{ V}$ Frequency=1 MHz	-	2000	-	pF
C_{oss}	Output Capacitance		-	420	-	
C_{rss}	Reverse Transfer Capacitance		-	15	-	
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50\text{ V}$, $V_{GEN}=10\text{ V}$, $R_G=3\Omega$, $I_{DS}=20\text{ A}$	-	18	-	ns
t_r	Turn-on Rise Time		-	25	-	
$t_{d(off)}$	Turn-off Delay Time		-	55	-	
t_f	Turn-off Fall Time		-	8.5	-	
Gate Charge Characteristics ^b						
Q_g	Total Gate Charge	$V_{DS}=50\text{ V}$, $V_{GS}=10\text{ V}$, $I_{DS}=20\text{ A}$	-	33	-	nC
Q_{gs}	Gate-Source Charge		-	7	-	
Q_{gd}	Gate-Drain Charge		-	7	-	

7. Typical Characteristics

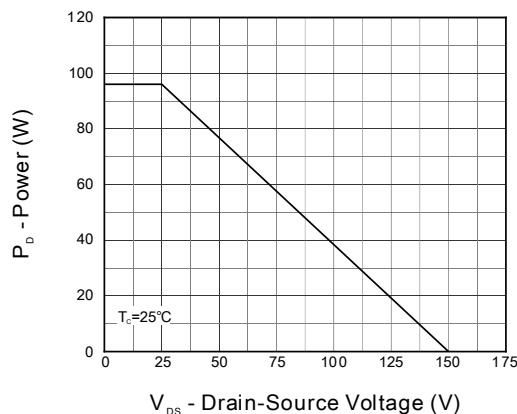


Figure 1. Output Characteristics

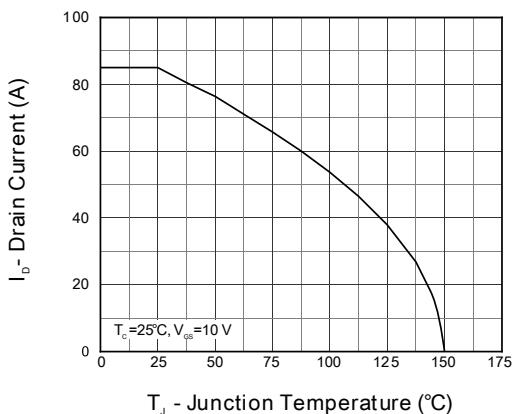


Figure 2. Current Capability

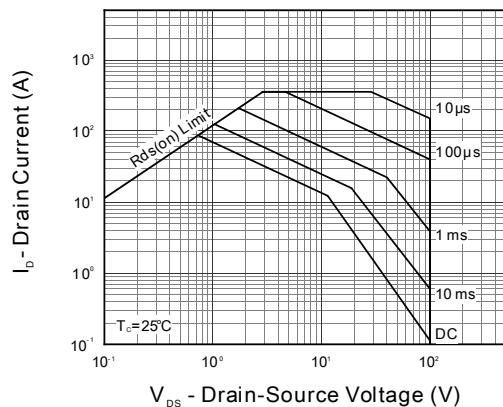


Figure 3. Safe Operation Area

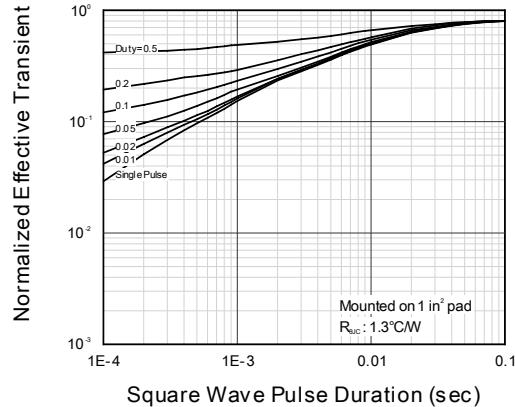


Figure 4. Transient Thermal Impedance

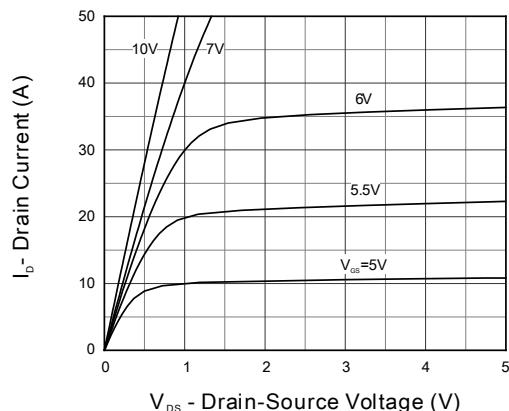


Figure 5. Output Characteristics

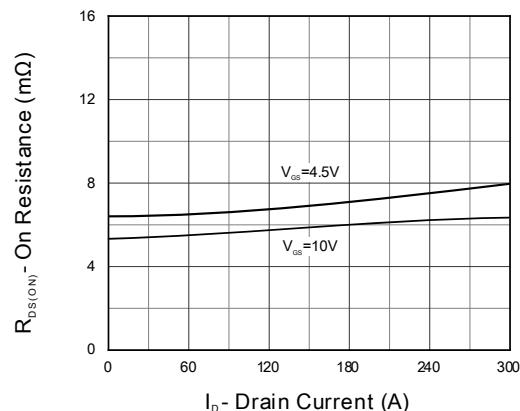


Figure 6. On Resistance

7. Typical Characteristics (cont.)

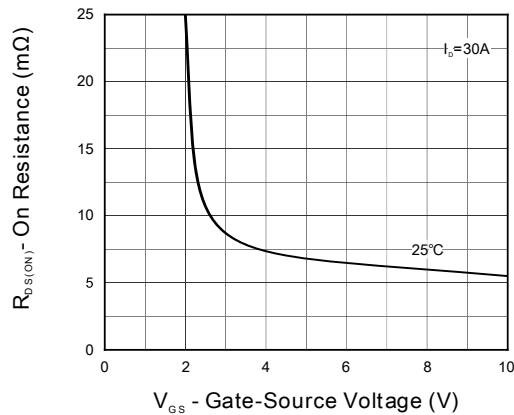


Figure 7. Transfer Characteristics

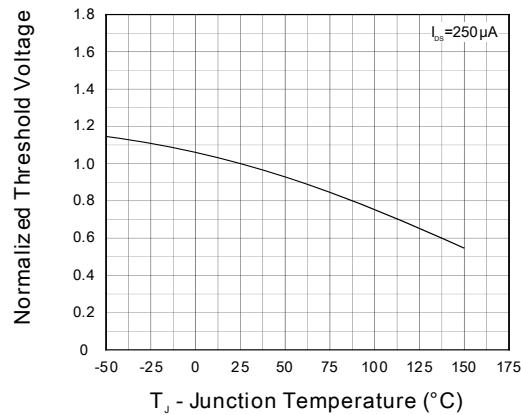


Figure 8. Normalized Threshold Voltage

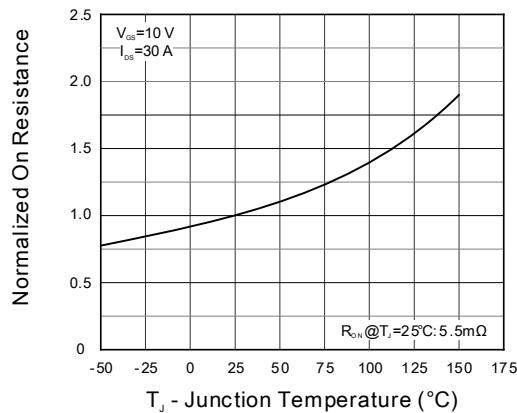


Figure 9. Normalized On Resistance

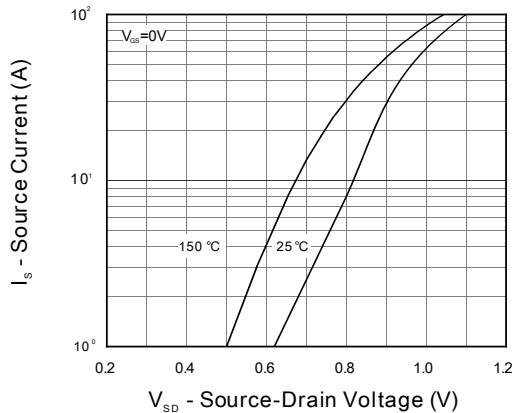


Figure 10. Diode Forward Current

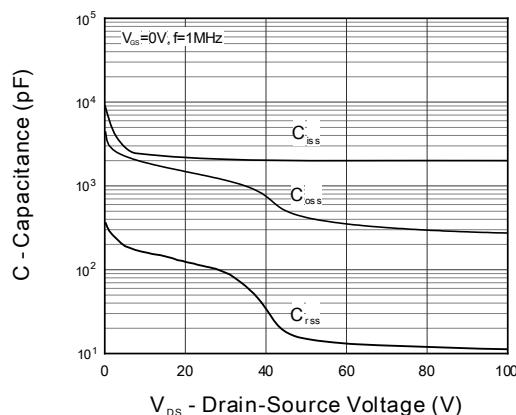


Figure 11. Capacitance

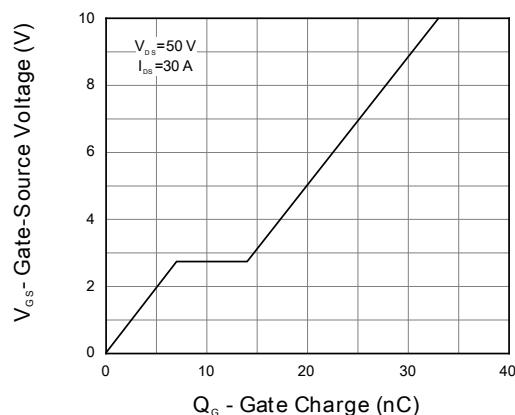
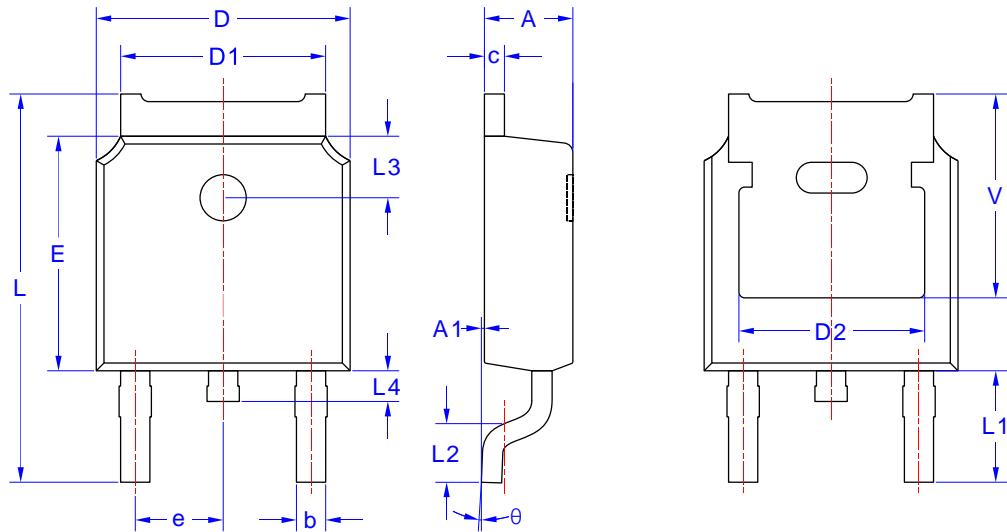


Figure 12. Gate Charge

8. Package Dimensions

TO-252 Package



Symbol	Dimensions in Millimeters	
	MIN	MAX
A	2.200	2.400
A1	0	0.127
b	0.660	0.860
c	0.460	0.580
D	6.500	6.700
D1	5.100	5.460
D2	4.830 REF.	
E	6.000	6.200
e	2.186	2.386
L	9.800	10.400
L1	2.900 REF.	
L2	1.400	1.700
L3	1.800 REF.	
L4	0.600	1.000
θ	0°	8°
V	5.600 REF.	